

IDC-A9,AMD,M

exchanged is illuminated through the density filter 55 and the reduced image of the pattern is exposed to another portion in the shot region on the wafer W so that regions (which are also referred to as "stitch portions") corresponding to the stitch portions 55a to 55d in Fig. 4(a) 4A in the adjacent reduced images are superposed and exposed. Thus, the reduced images of the patterns of the reticles in the shot region on the wafer W are transferred while carrying out a screen stitch in the X and Y directions. The amount of integral exposure which is almost uniform is given over the whole shot region by using the density filter 55.

Please replace the ~~paragraph~~ beginning on page <sup>33</sup>~~34~~, line <sup>24</sup>~~1~~, with the following rewritten

N/A 8/18/06

~~paragraph:~~

IDC-A10,AMD

Fig. 5 shows a large projected image exposed to one shot region on the wafer W in Fig. 1 by the exposure carrying out the screen stitch in the present example. In Fig. 5, rectangular projected images 30A, 30B, 30C and 30D constituted by the reduced images of the patterns of different reticles are exposed with stitch portions 30AB and 30CD in a boundary portion in the X direction and stitch portions 30AC and 30BD in a boundary portion in the Y direction superposed double, respectively. In a rectangular stitch portion 31 in which four projected images 30A to 30D are provided adjacently to each other, furthermore, the rectangular corner portions of the four projected images 30A to 30D are superposed fourfold and exposed. In this case, if the rotation error of the density filter 55 in Fig. 4(a) 4A and the reticle on the reticle stage 21 in Fig. 1 is not completely eliminated by the positioning device 5, it is preferable that the reticle stage 21 should be rotated to set off the rotation error and the coordinate system of the wafer stage 25 should be corrected by the rotation error, and the wafer W should be stepped obliquely based on the corrected coordinate system. Consequently, the error (dose error) of the amount of exposure in the stitch portion can be reduced.